(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
12 June 2008 (12.06.2008)

PCT

(10) International Publication Number
WO 2008/070772 A1

(51) International Patent Classification:
*G06F 17/50* (2006.01)

(21) International Application Number:
PCT/US2007/086635

(22) International Filing Date:
6 December 2007 (06.12.2007)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
60/868,769 6 December 2006 (06.12.2006) US
11/950,961 5 December 2007 (05.12.2007) US

(71) Applicant *(for all designated States except US)*: **KLA-TENCOR CORPORATION** [US/US]; 160 Rio Robles, San Jose, California 95134 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **FOUQUET, Christophe** [US/US]; 825 E. Evelyn Ave., Sunnyvale, California 94086 (US). **ABBOTT, Gordon** [US/US]; 341 Kottinger Drive, Pleasanton, California 94566 (US). **CHANG, Ellis** [US/US]; 19795 Farwell Avenue, Saratoga, c 95070 (US). **SAIDIN, Zain K.** [US/US]; 545 Edinburgh Street, San Mateo, California 94402 (US).

(74) Agents: **MEWHERTER, Ann Marie** et al.; Baker & McKenzie LLP, 1114 Avenue of the Americas, New York, New York 10036 (US).

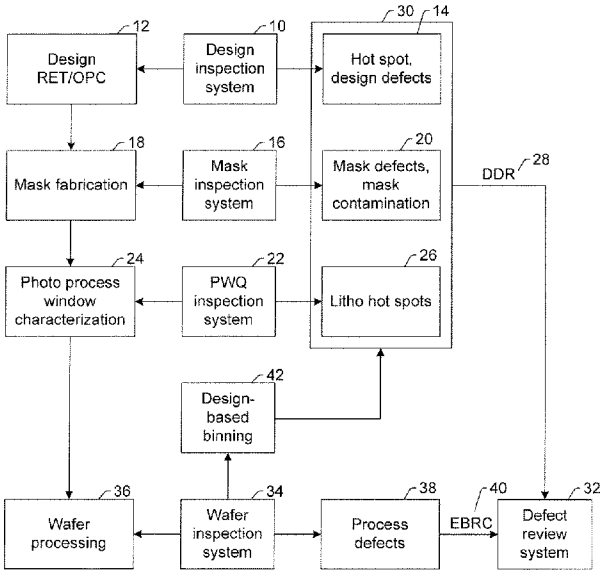
(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

**Published:**
— *with international search report*

*[Continued on next page]*

(54) **Title:** METHODS, DESIGNS, DEFECT REVIEW TOOLS, AND SYSTEMS FOR DETERMINING LOCATIONS ON A WAFER TO BE REVIEWED DURING DEFECT REVIEW




(57) **Abstract:** Various methods, designs, defect review tools, and systems for determining locations on a wafer to be reviewed during defect review are provided. One computer-implemented method includes acquiring coordinates of defects detected by two or more inspection systems. The defects do not include defects detected on the wafer. The method also includes determining coordinates of the locations on the wafer to be reviewed during the defect review by translating the coordinates of the defects into the coordinates on the wafer such that results of the defect review performed at the locations can be used to determine if the defects cause systematic defects on the wafer.

WO 2008/070772 A1

— *before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments*